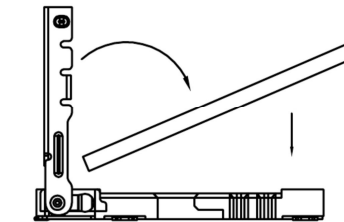
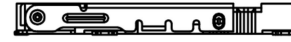


NANO SIM CARD

SIM CARD	
PIN No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



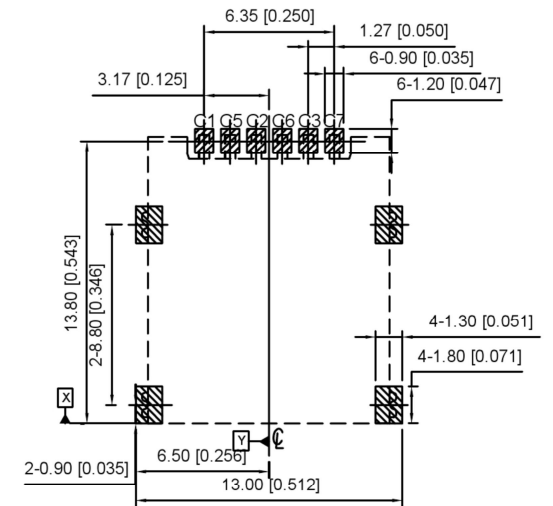
STEP 1 INSERT Nano-SIM CARD



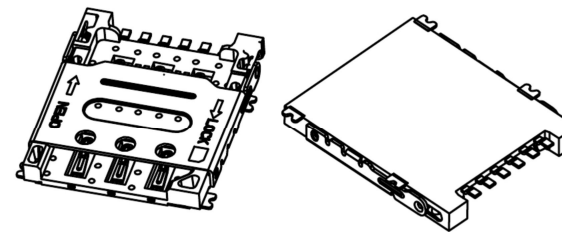
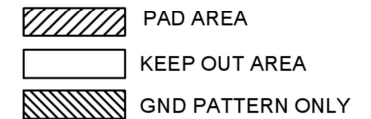
STEP 2 PUSH THE SHELL



STEP 3 FINISH



RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE  $\pm 0.05$



3D VIEW

NOTE:

1.材料 Material:

- 1-1 胶壳 Housing: High Temperature Thermoplastic.  
(LCP S475j Color Black UL94V-0)
- 1-2 触点 Contact: Phosphor Bronze (C5210R-HT=0.15  $\pm$  0.02mm)
- 1-3 盖 Cover: SUS301-HT=0.20  $\pm$  0.03mm

2.电镀 Plating:

- 接触端子 Contact terminal:
- 接触电阻 Contact area: Gold 1u" Min.
- 焊料区 Solder area: Gold 0.8u" Min
- 底镀 Underplating: Ni overall 50u" Min,



3.规格 Specification:

- 3-1.接触电阻 CONTACT RESISTANCE: 50 Milliohms Max
- 3-2.绝缘电阻 INSULATION RESISTANCE: 1.000 Megohms Min.
- 3-3.绝缘耐压 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1MINUTE.
- 3-4.工作温度范围 OPERATION TEMPERATURE RANGE: -25C~+70
- 3-5.耐用性 DURABILITY: 3000 CYCLES

4. Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC

5. Part Must Comply Taisol HFWD-3-1-091 Specification.

6. Recommending A Metal More Than 0.15mm Thick.

REVISIONS				UNSPECIFIED TOLERANCES		DSND	SCALE: N/A	MODEL TYPE: SIM CARD CONN		
			ANGULAR	$\pm 5^\circ$		DWN	VIEW: 	PART NO.: XKNANO-1150		
			$L \leq 4$	$\pm 0.2$		CHKD	UNIT: mm/in	DWG NO.:		
			$4 < L \leq 16$	$\pm 0.3$		APPD	SIZE: A4			
			$16 < L \leq 63$	$\pm 0.4$			WEIGHT	SHEET	REVISION	
			$L > 63$	$\pm 0.5$				1/1	A0	
www.alpsr.com www.gdxjdz.com www.xbswitch.com					DONG GUAN XI BANG ELECTRONIC CO., LTD					